

Notice of References Cited

Application/Control No.

09/483,881

Applicant(s)/Patent Under
Reexamination
AHN ET AL.

Examiner

Ha T. Nguyen

Art Unit

2812

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U.S. PATENT DOCUMENTS

| * | | Document Number Country Code-Number-Kind Code | Date MM-YYYY | Name | Classification |
|---|---|--|-----------------|---------------|----------------|
| | A | US-5034799 / | 07-1991 | Tomita et al. | 438 |
| | B | US-6372622 / | 04-2002 | Tan et al. | 438 |
| | C | US- | | | |
| | D | US- | | | |
| | E | US- | | | |
| | F | US- | | | |
| | G | US- | | | |
| | H | US- | | | |
| | I | US- | | | |
| | J | US- | | | |
| | K | US- | | | |
| | L | US- | | | |
| | M | US- | | | |

FOREIGN PATENT DOCUMENTS

| * | | Document Number Country Code-Number-Kind Code | Date MM-YYYY | Country | Name | Classification |
|---|---|--|-----------------|---------|------|----------------|
| | N | | | | | |
| | O | | | | | |
| | P | | | | | |
| | Q | | | | | |
| | R | | | | | |
| | S | | | | | |
| | T | | | | | |

NON-PATENT DOCUMENTS

| * | | Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages) | | | | |
|---|---|---|--|--|--|--|
| | U | Bernier et al., "Laser processing of palladium for selective electroless copper plating", SPIE vol.2045, 1994, pp.330-337 | | | | |
| | V | | | | | |
| | W | | | | | |
| | X | | | | | |

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

in 6-11-02